

TechConnect Ventures

Sprint Challenge Brief:

Materials and enabling technologies for flexible stretchable electronics

BACKGROUND

On behalf of our global corporate partners, TechConnect Ventures is seeking innovations for materials and technologies that can be used in flexible or stretchable electronics. The emerging field of stretchable electronics enables electronic devices to be built from electronic circuits deposited onto stretchable substrates or being embedded into a stretchable material. Their application is widespread including wearable electronics, health monitoring, sensors for cyber-skin, and bio-compatible implantable devices. The material space for these applications is large and includes organic, inorganic, and hybrid conducting and dielectric materials.

REQUIREMENTS

Relevant areas of interest include, but are not limited to, materials and technologies for:

- Structure design strategies such as wavy structure configuration, island-interconnect configuration, and others
- Stretchable conductors and electrodes
- Energy conversion and storage devices for stretchables
- Conductive printing on non-planar surfaces
- 3D printing methods for flexible electronics
- Artificial skins and e-textiles
- Stretchable sensors and biosensors

BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should review the [Rules](#) and [Guidelines](#) provided on the Sprint page for details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com